



# YETDA INDUSTRY LTD.

## Technical Data Sheet

MODEL NO : S3535ANPW4P-M-3W

3535 Package 3.45\*3.45mm Chip LEDs

### Features :

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

### Applications :

- Lighting
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Pure-White	Yellow Diffused

### Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Color Temperature	I <sub>F</sub> =700mA	CCT		4000		K
Forward voltage	I <sub>F</sub> =700mA	V <sub>F</sub>	3.4	.	4.4	V
Chromaticity Coordinates		X		0.380		
		Y		0.380		
Luminous Flux	I <sub>F</sub> =700mA	Lm	200	240	275	Lm
Viewing angle at 50% I <sub>v</sub>	I <sub>F</sub> =700mA	2θ 1/2	--	120	--	Deg
Reverse current	V <sub>r</sub> =5V	I <sub>R</sub>	--	∅ -	10	μA

### Absolute Maximum Ratings(Ta=25°C)

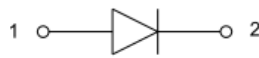
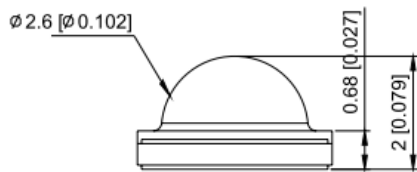
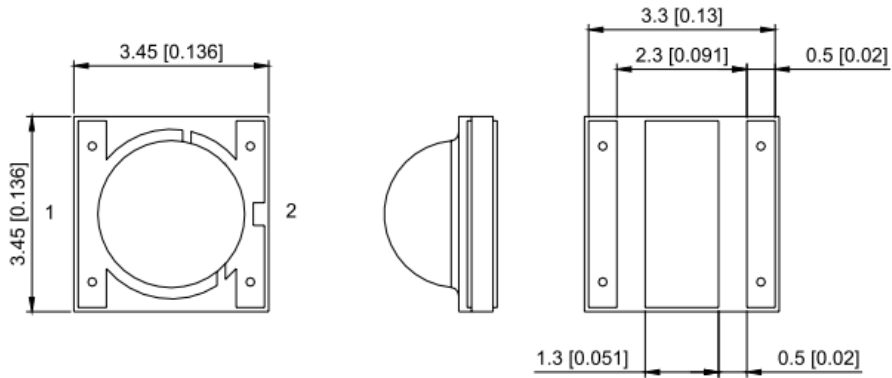
Parameter	Symbol	Value	Unit
		White	
Power dissipation	P <sub>d</sub>	2	W
Forward current	I <sub>F</sub>	700	mA
Reverse voltage	V <sub>R</sub>	5	V
Operating temperature range	T <sub>op</sub>	-40 ~+85	°C
Storage temperature range	T <sub>stg</sub>	-40 ~+100	°C
Peak pulsing current (1/8 duty f=1kHz)	I <sub>FP</sub>	1	A

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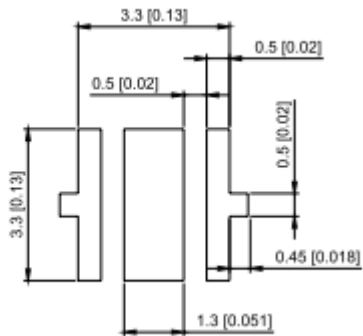


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## PACKAGING DIMENSIONS

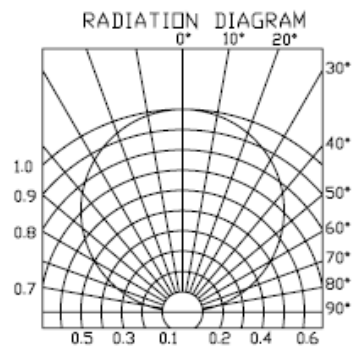
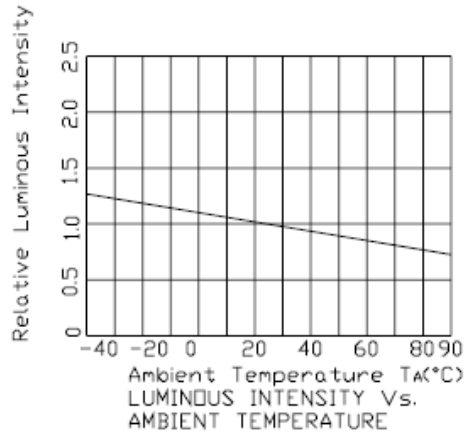
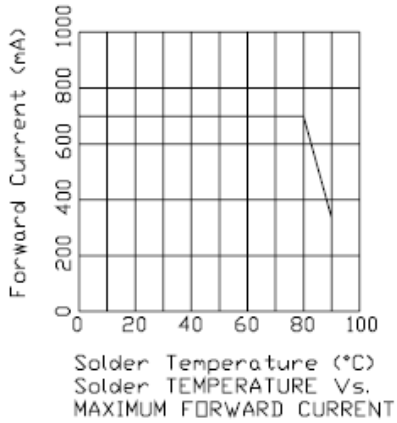
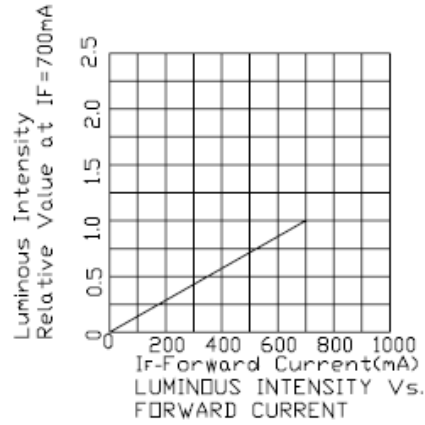
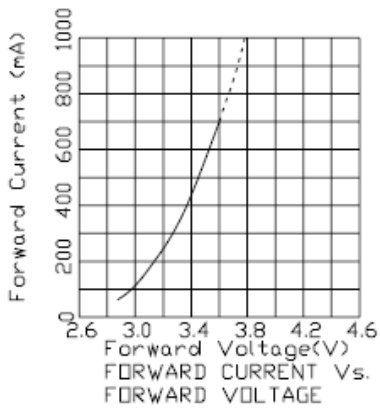


## Recommended soldering pattern





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## Precautions For Use :

### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen )

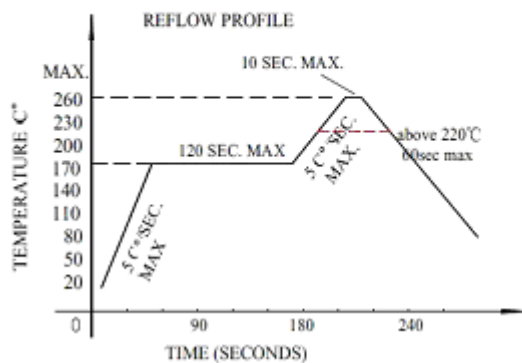
### Storage

1. The operation of temperature and R.H. are :  $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$  , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating reagent. Considering the tape life, we suggest our customers to use our products within 1.5 year ( from production date ) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.

## ■ Reflow Temp/Time

### ■ Temperature-profile (Surface of circuit board)

Use the following conditions shown in the figure.



## NOTES:

1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### ■ Soldering iron

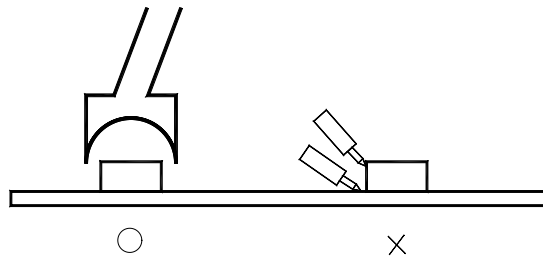
Basic spec is  $\leq 5\text{sec}$  when  $260^{\circ}\text{C}$  . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$  ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable . Surface temperature of the device should be under  $230^{\circ}\text{C}$  .



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## ■ Rework

1. Customer must finish rework within 5 sec under 260°C.
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.

## Dimensions of Tape (Unit: mm)

